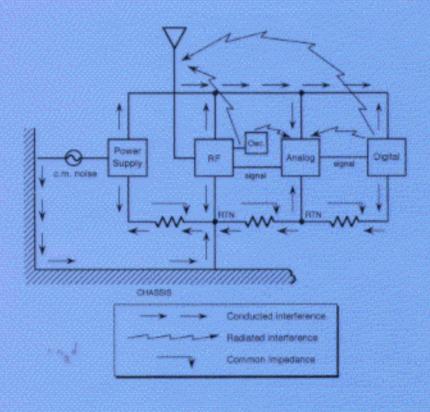
## Electromagnetic Compatibility

**Principles and Applications** 

Second Edition, Revised and Expanded



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## **Contents**

Prefa	ice		ii
Chapter 1 Introduction to EMI and the Electromagnetic Environment			:
1.1	Intr	oduction to electromagnetic interference (EMI)	
1.2	Intr	oduction to electromagnetic interference regulations	
1.3	1.3 Electromagnetic environment		4
Refe	rences	•	17
Chap	oter 2	Introduction to E and H, Near and Far Fields, Radiators,	
		Receptors, and Antennas	19
2.1	Stat	ic and quasi-static fields	20
2.2		ctric waves on wires and in free space	26
2.3		iated power	42
2.4	Uni	ts of measurement	45
2.5	Rec	eiving properties of an antenna	46
2.6		ple, easily constructed E and H field antennas	62
2.7	Non	ionizing electromagnetic field exposure safety limits	75
2.8	Con	nputer programs	84
Refer	ences		93
Char	ter 3	Typical Sources and Characteristics of Radiated and	,
•		Conducted Emissions	95
3.1	Intro	oduction to noise sources	. 95
3.2		rier transform methods and computer programs	106
3.3	Case	Study 3,1: Noise levels generated by dc-to-dc converters	107
3.4	Trar	smitter generated noise	118
Refer	ences		119
Chap	ter 4	Crosstalk and Electromagnetic Coupling Between PCB Tracks,	
		Wires, and Cables	121
4.1	Intro	oduction to crosstalk and electromagnetic coupling	121
4.2	Capa	acitive crosstalk and electric field coupling between wires and cables	123
4.3	Indu	ctive crosstalk and magnetic field coupling between wires and cables	131
4.4	Com	bined inductive and capacitive crosstalk	141
Refer	ences		169

vi	Contents
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Chapt	er 5 Components, Emission Reduction Techniques, and Noise Immunity	171
5.1	Components	171
5.2	Emission reduction techniques	228
5.3	Noise immunity	232
5.4	Transient protection	269
Addres	sses of manufacturers mentioned in this Chapter	281
Refere	nces	282
Chapt	er 6 Electromagnetic Shielding	283
6.1	Reflection, absorption, and shielding effectiveness	283
6.2	Shielding effectiveness	289
6.3	New shielding materials: conductive paints and thermoplastics, plastic	205
- 4	coatings, and glue	297
6.4	Seams, joints, ventilation, and other apertures	304
6.5	Gasketing theory, gasket transfer impedance, gasket type, and surface finish	328
6.6	Practical shielding and limitation on effectiveness	348
6.7	Compartmentalization	349
6.8	Shielding effectiveness of buildings	349
6.9	Computer program for evaluating shielding effectiveness	352
Refere	nces	354
Chapt	er 7 Cable Shielding, Coupling from E and H Fields, and Cable	
	Emissions	357
7.1	Introduction to cable coupling and emissions	357
7.2	Cable shielding effectiveness/transfer impedance	357
7.3	Shield termination effects on transferred voltage	385
7.4	Coupling from E and H fields	387
7.5	Shield termination	398
7.6	Emissions from cables and wires	403
7.7	Reduction in the emissions of E and H fields from cables	415
7.8	Shielded connectors, backshells, and other shield termination techniques	415
7.9	Practical level of shielding required to meet MIL-STD/DO-160C or	
	commercial radiated emission requirements	426
Refere	ences	430
Chapt	ter 8 Grounding and Bonding	433
8.1	Introduction to grounding	433
8.2	Safety grounds, earth grounds, and large-system grounding	434
8.3	Signal ground and power ground	443
8.4	Guidelines for signal grounding	453
8.5	Power and grounding diagrams	454
8.6	Grounding for lightning protection	454
8.7	Bonding	465
Refere	· · · · · · · · · · · · · · · · · · ·	476

Contents	•	vii
Chapter 9	EMI Measurements, Control Requirements, and Test Methods	477
9.1 In	troduction	477
9.2 Te	est equipment	478
	iagnostic measurements •	495
9.4 Co	ommercial EMI requirements and measurement	502
9.5 St	nielded rooms, anechoic chambers, transmission lines, and cell antennas	567
9.6 M	ilitary EMI requirements and measurement techniques	589
	ΓCA/DO-160 requirements	635
Reference	S ·	638
Chapter 1	0 Systems EMC and Antenna Coupling	639
10.1 Sy	stem-level EMC	<b></b>
	ntenna-coupled EMI	639
	nbient site predictions and surveys	648
10.4 Ca	use Study 10.3: Coupling into HV ac line from HF phased-array radar	671
References	s	678 681
		001
Chapter 11 Printed Circuit Boards		683
11.1 Int	troduction	683
11.2 Pri	inciples of radiation from printed circuit boards	683
11.3 Lo	w-level radiation PCB layout	685
	omparison of logic types	705
	rcuit-level reduction techniques	710
	B grounding	714
	ielding a printed circuit board	724
11.8 PC	B radiation, crosstalk prediction, and CAD programs	729
	B layout case studies	737
11.10 Inc	creased printed circuit board immunity	746
References		747
Chapter 1	2 EMI and EMC Control, Case Studies, EMC Prediction	
	Techniques, and Computational Electromagnetic Modeling	749
	fC control	749
	II investigations	753
12.3 EM	IC predictions: general approach	762
12.4 EM	IC, computational electromagnetic modeling, and field solver computer	
pro	grams	786
References		812
Appendix 1	Characteristic Impedance of Conductors, Wires, and Cables	813
Appendix 2	2 Units and Conversion Factors	817

Appendix 3	Electric Field Strength to Magnetic Field to Power Density Conversions	819
Appendix 4	Commonly Used Related Formulas	821
Appendix 5	Data on Bare Solid Copper Wire (Dimensions, Weight, and Resistance)	825
	and the first of the second	
Index		827